

ABSTRACT OF THE DISCLOSURE

A semiconductor device is manufactured in a method including the steps of: abrasing a surface of a wafer opposite that thereof having a solder ball serving as an external connection electrode; and reinforcing the abraded surface with resin serving as a back-surface reinforcement member. More specifically, the resin is resin of rubber type, silicone type, epoxy type, polyimide type or urethane type. Preferably, previously grinding the surface to be abraded is previously ground to produce the device in a reduced process time. The structure can advantageously prevent a solder connection from breaking as an LSI chip fails to bend in response when the entire package receives force and thus bends.